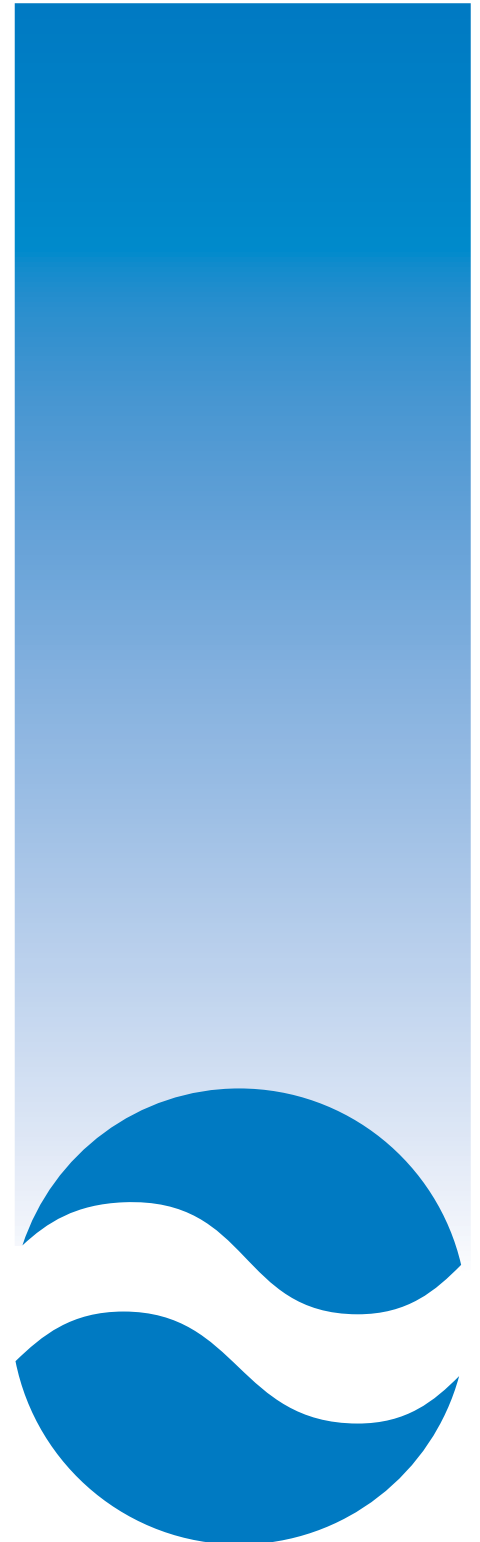


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May 2014

JOINT INDUSTRY STANDARD

Solderability
Tests for
Printed Boards



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with Amendments 1 & 2**

Solderability Tests for Printed Boards

Developed by the Printed Circuit Board Solderability Specifications Task Group (5-23a) of the Assembly and Joining Committee (5-20) of IPC

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Contact:

IPC

3000 Lakeside Drive, Suite 309S
Bannockburn, IL 60015-1249
Phone (847) 615-7100
Fax (847) 615-7105

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Assembly and Joining Committee

Co-Chair
Daniel Foster
Missile Defense Agency

Co-Chair
Leo P. Lambert
EPTAC Corporation

Vice Chair
Dr. Karen A. Tellefsen
Alpha Assembly Solutions

Printed Circuit Board Solderability Specifications Task Group

Chair
Gerard A. O'Brien
Solderability Testing & Solutions, Inc.

Vice Chair
Michah Pledger
Vivant, Inc.

Technical Liaison of the IPC Board of Directors

Robert Neves
Microtek (Changzhou) Laboratories

Printed Circuit Board Solderability Specifications Task Group Automotive Systems Company of America

David Adams, Rockwell Collins
Greg Alexander, Ascentech, LLC
Elizabeth Allison, NTS - Baltimore
Chris Alter, Honeywell International
Emmanuel Anglade, Metronelec
Dr. Raiyomand Aspandiar, Intel Corporation
Zohreh Bagheri, Celestica
Robert Bagsby, Rockwell Collins
Frank S. Bai, Taiwan Printed Circuit Association
Chris Ball, Valeo Inc.
Joseph Barber, Raytheon Missile Systems
Lisa Barnes, NTS - Chicago
Dr. Martin Bayes, TE Connectivity
Bill Bear, Raytheon Company
Mary Bellon
Frederick Beltran, L-3 Communications
Beatriz Bennett, Lockheed Martin Missiles & Fire Control
James Bielick, IBM Corporation
Wendi Boger, TTM Technologies
Mumtaz Bora, Peregrine Semiconductor
Trevor Bowers, Adtran Inc.
Scott Bowles, L-3 Fuzing and Ordnance Systems, Cincinnati

Steven Bowles, ALL Flex LLC
Edwin Bradley, Motorola Solutions, Inc.
Jason Bragg, Celestica
Peter Bratin, ECI Technology, Inc.
Tim Brown, ACME Training & Consulting
Mark Buechner, BAE Systems
Vanja Bukva, Teledyne Dalsa
Martin Bunce, MacDermid Enthone Electronics Solutions
Fritz Byle, Astronautics Corp. of America
William Cardinal, NEO Technology Solutions
Thomas Carlstrom, Ericsson AB - Kista
Thomas Carroll, Boeing Company
Mary Carter Berrios, KEMET Electronics Corp.
Byron Case, L-3 Communications
Ratna Reddy Chada, L-3 Fuzing and Ordnance Systems, Cincinnati
Srinivas Chada, Stryker Instruments
Calette Chamness, U.S. Army Aviation & Missile Command
Laya (Yan) Chen, Microtek (Changzhou) Laboratories
Dr. Beverley Christian, HDP User Group

James Clark, Multek Flexible Circuits, Inc.
Lenora Clark, MacDermid Enthone Electronics Solutions
Michael Collier, Teledyne Advanced Electronic Solutions
Michael Connors, NTS - Chicago
David Corbett, DLA Land and Maritime
Alejandro Cruz, Jabil Mexico
James Daggett, Raytheon Company
Richard Davidson, Honeywell Aerospace
William Dieffenbacher, BAE Systems
Glenn Dody, Dody Consulting
Miguel Dominguez, Continental Temic SA de CV
J. Donovan
John Dovolos, Holaday Circuits Inc.
Don Dupriest, Lockheed Martin Missiles & Fire Control
Richard Edgar, Tec-Line Inc.
Theodore Edwards
Ernst Eggelaar, Microtronic
Harold Ellison, Quantum Corporation
Howard Feldmesser, Johns Hopkins University
Julie Filips, Elbit Systems of America

William Fox, Lockheed Martin Missile & Fire Control	Gregg Klawson, General Dynamics Mission Systems	Suzanne Nachbor, Honeywell Aerospace Minneapolis
Darrell Freiwald, Northrop Grumman Systems Corporation	Christian Klein, Robert Bosch GmbH	Graham Naisbitt, Gen3 Systems Limited
Dennis Fritz, MacDermid Enthone Electronics Solutions	Jason Koch, Robisan Laboratory Inc.	Gary Nicholls, Metalor Technologies USA
Tom Fujikawa, Seika Machinery, Inc.	Wei Koh, Pacrim Technology	Debora Obitz
Mark Fulcher, Continental Automotive Systems	Kelly Kovalovsky, i3 Electronics	Patrick O'Keefe, Holaday Circuits Inc.
Gerald Gagnon, Extech Instruments Corporation	Richard Kraszewski, Plexus Corp.	Michael Paddack, Boeing Company
Mahendra Gandhi, Northrop Grumman Aerospace Systems	Vijay Kumar, Lockheed Martin Missile & Fire Control	Dr. J. Lee Parker, JLP
Rigo Garcia, NASA Goddard Space Flight Center	William Kummer, Raytheon Company	Michael Pavlov, ECI Technology, Inc.
Karl Gerdom, Atotech Deutschland GmbH	Mark Kwoka, Intersil Corporation	Timothy Pitsch, Plexus Corporation
Reza Ghaffarian, Jet Propulsion Laboratory	Leo Lambert, EPTAC Corporation	John Potenza, Lockheed Martin Mission Systems & Training
Andrew Giamis, Andrew Corporation	Kevin Lamelin, TTM Technologies, Inc.	Jagadeesh Radhakrishnan, Intel Corporation
Cynthia Gomez, Continental Temic SA de CV	Theron Lewis, IBM Corporation	John Radman, NTS - Denver
Constantino Gonzalez, ACME Training & Consulting	Anna Lifton, Alpha Assembly Solutions	Gustavo Ramos, Atotech Deutschland GmbH
Ty Gragg, Unicircuit Inc.	Daniel Lipps, L-3 Fuzing and Ordnance Systems, Cincinnati	Randy Reed, R. Reed Consultancy LLC
Rachel Grinvalds, Rockwell Collins	Jianfeng Liu, ZTE Corporation	Henry Rekers, Schneider Electric
Donald Gudeczauskas, Uyemura International Corp.	Zhe (Jacky) Liu, ZTE Corporation	Jose Rios, Massachusetts Institute of Technology
Vicka Hammill, Honeywell Inc. Air Transport Systems	Kyle Loomis, Kester	Ivan Roman, Continental Temic SA de CV
Dr. Carol Handwerker, Purdue University	Todd MacFadden, Bose Corporation	Brenda Ross, Air Products & Chemicals
Shirley He, The 5th Electronic Institute of MII	Dr. Brian Madsen, Continental Automotive Systems	Richard Rumas, Honeywell Canada
Steven Herrberg, Raytheon Systems Company	James Maguire, Intel Corporation	William Russell, Raytheon Professional Services LLC
Gaston Hidalgo, Samsung Electronics America	Chris Mahanna, Robisan Laboratory Inc.	Christopher Ryder, AT&S Austria Technologie & Systemtechnik AG
Mike Hill, TTM Technologies	Seth Maitlen, TTM Technologies	Karl Sauter, Oracle America, Inc.
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Mitchell Holtzer, Alpha Assembly Solutions	Israel Martinez Montano, Continental Automotive Nogales S.A. de C.V.	Martin Scionti, Raytheon Missile Systems
Chee Chung Hoong, Keysight Technologies	Matthew McQueen, NSW Crane	Rudy Sedlak, RD Chemical Co.
Dr. Christopher Hunt, Gen3 Systems Limited	Arnie Melby, Appareo Systems, LLC	Jeff Seekatz, Raytheon Company
Richard Iodice, Raytheon Company	Peter Menez	William Sepp, Technic Inc.
Sharissa Johns, Lockheed Martin Missiles & Fire Control	Renee Michalkiewicz, NTS - Baltimore	Jose Servin Olivares, Continental Temic SA de CV
Shantanu Joshi, Koki Solder America Inc.	Roger Miedico, Raytheon Company	Gilbert Shelby, Raytheon Systems Company
	George Milad, Uyemura International Corp.	Russell Shepherd, NTS - Anaheim
	William Miller, Panasonic Automotive Systems Company of America	Lowell Sherman, DLA Land and Maritime
	James Monarchio, TTM Technologies, Inc.	Akikazu Shibata, JPCA-Japan Electronics Packaging and Circuits Association
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	Kil-Won Moon, NIST - Gaithersburg	
	Terry Munson, Foresite, Inc.	

Dawn Skala, Sandia National Laboratories, Calif.	Dr. Brian Toleno, Microsoft Corporation	Maureen Williams, NIST - Gaithersburg
Bradley Smith, Allegro Microsystems Inc.	Bradley Toone, L-3 Communications	Russell Winslow, Six Sigma
John Snyder, Inventec Performance Chemicals	Umut Tosun, ZESTRON Americas	Jere Wittig
David Sommervold, The Bergquist Company/Henkel Electronic Materials LLC	Kristen Troxel, Hewlett-Packard Company	Michael Wolverson, Raytheon Systems Company
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Keith Sweatman, Nihon Superior Co., Ltd.	Scott Ubl, Plexus Corporation	Yung-Herng Yau, MacDermid Enthone Electronics Solutions
Dr. Karen Tellefsen, Alpha Assembly Solutions	Crystal Vanderpan, UL LLC	Tony Yim, TTM Technologies Zhongshan
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Solderability Tests for Printed Boards

1 GENERAL

1.1 Scope This standard prescribes test methods, defect definitions, and illustrations for assessing the solderability of printed wiring board surface conductors, attachment lands, and plated-through holes (PTHs). This standard is intended for use by both user and supplier.

This standard is not intended to verify the potential of successful processing at assembly or to evaluate design impact on wettability. This standard describes procedures or methods to determine the acceptable wettability of a surface finish. Wettability can be affected by handling, finish application, and environmental conditions.

1.2 Purpose This standard describes solderability determinations that are made to verify that the printed board fabrication processes and subsequent storage have had no adverse effect on the solderability of those portions of the printed board intended to be soldered. Reference coupons or representative portions of a printed board may be used. Solderability is determined by evaluation of a test specimen which has been processed as part of a panel of boards and subsequently removed for testing per the method selected.

1.3 Objective To provide solderability test methods to determine the acceptance of printed board surface conductors, attachment lands, and PTHs to wet easily with solder, and to withstand the rigors of the printed board assembly processes.

1.3.1 Definition of Requirements The word “shall” is used in the text of this document wherever there is a requirement for materials, preparation, process control, or acceptance of a soldered connection or a test method. The word “should” reflects “best processing techniques” and is used to reflect general industry practices and a suggestion for guidance only.

1.3.2 Document Hierarchy In the event of conflict, the following descending order of precedence applies:

- a. Procurement documentation AABUS, which should include expected shelf life requirements if stored and handled properly.
- b. Master drawing or master assembly drawing reflecting the user’s detailed requirements.
- c. When required by the customer or per contractual agreement, this document, J-STD-003.
- d. Other documents, to the extent specified by the customer.

1.4 Classification Three general classes have been established to reflect progressive increases in sophistication, functional performance requirements, and testing/ inspection frequency as defined in the IPC-6010 series of documents.

The user is responsible for defining the product class. The product class should be stated in the procurement documentation package.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

CLASS 3 High Performance Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

Printed board performance classes do not dictate the surface finish durability rating that may be specified. Category 2/ Category A durability is the default coating durability rating.

This standard relies on input from the 4-14 plating process subcommittee and the 4500 series of printed board surface finish documents generated in that subcommittee to determine the durability rating potential for each specified finish. This document and the appropriate 4500 series document should be considered complimentary to one another.